

## Description

The 9DBU0831 is a member of IDT's 1.5V Ultra-Low-Power (ULP) PCIe family. The device has 8 output enables for clock management and 3 selectable SMBus addresses.

## Recommended Application

1.5V PCIe Gen1-2-3 Zero Delay/Fanout Buffer (ZDB/FOB)

## Output Features

- 8 – 1-167MHz Low-Power (LP) HCSL DIF pairs

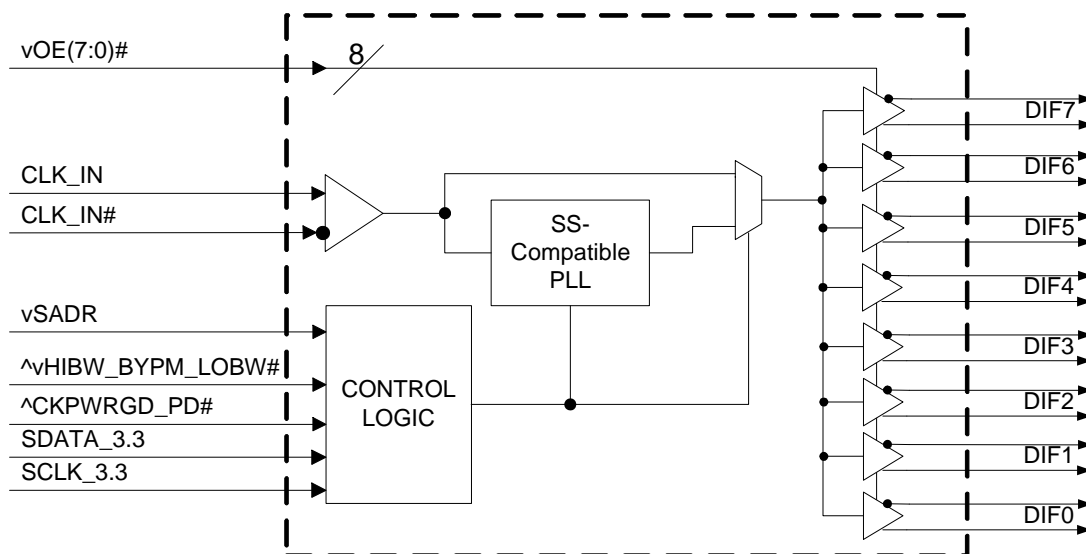
## Key Specifications

- DIF cycle-to-cycle jitter <50ps
- DIF output-to-output skew < 75ps
- DIF phase jitter is PCIe Gen1-2-3 compliant
- DIF bypass mode *additive* phase jitter is <300fs rms for PCIe Gen3
- DIF bypass mode *additive* phase jitter <350fs rms for 12k-20MHz

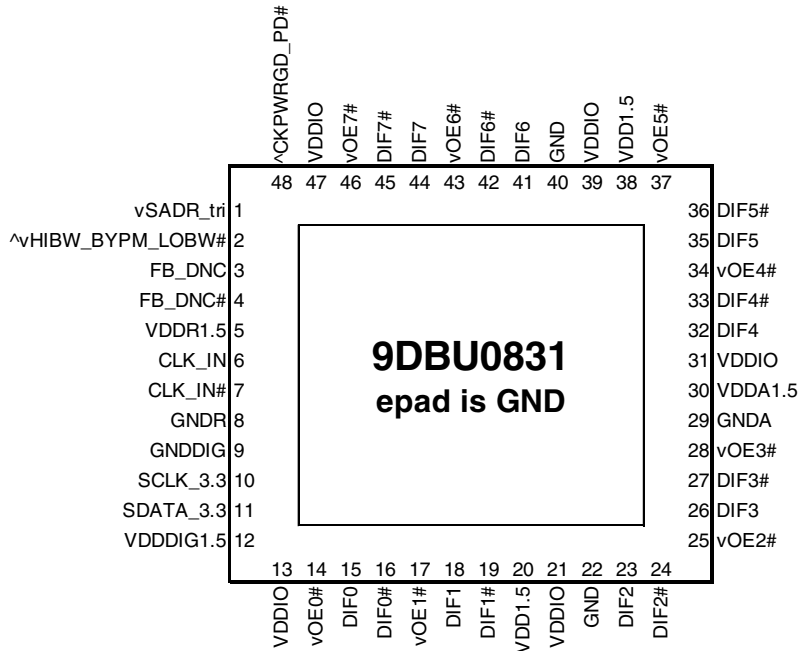
## Features/Benefits

- LP-HCSL outputs; save 16 resistors compared to standard HCSL outputs
- 53mW typical power consumption in PLL mode; eliminates thermal concerns
- Outputs can optionally be supplied from any voltage between 1.05 and 1.5V; maximum power savings
- Spread Spectrum (SS) compatible; allows SS for EMI reduction
- OE# pins; support DIF power management
- HCSL-compatible differential input; can be driven by common clock sources
- SMBus-selectable features; optimize signal integrity to application
  - slew rate for each output
  - differential output amplitude
- Pin/SMBus selectable PLL bandwidth and PLL Bypass; optimize PLL to application
- Outputs blocked until PLL is locked; clean system start-up
- Device contains default configuration; SMBus interface not required for device control
- Three selectable SMBus addresses; multiple devices can easily share an SMBus segment
- 3.3V tolerant SMBus interface works with legacy controllers
- Space saving 48-pin 6x6mm VFQFPN; minimal board space

## Block Diagram



## Pin Configuration



**48-pin MLF, 6x6 mm, 0.4mm pitch**

- ^v prefix indicates internal 120KOhm pull up *AND* pull down resistor (biased to VDD/2)
- v prefix indicates internal 120KOhm pull down resistor
- ^ prefix indicates internal 120KOhm pull up resistor

### SMBus Address Selection Table

	SADR	Address	+ Read/Write bit
State of SADR on first application of CKPWRGD_PD#	0	1101011	x
	M	1101100	x
	1	1101101	x

### Power Management Table

CKPWRGD_PD#	CLK_IN	SMBus OEx bit	OEx# Pin	DIFx		PLL
				True O/P	Comp. O/P	
0	X	X	X	Low	Low	Off
1	Running	0	X	Low	Low	On <sup>1</sup>
1	Running	1	0	Running	Running	On <sup>1</sup>
1	Running	1	1	Low	Low	On <sup>1</sup>

1. If Bypass mode is selected, the PLL will be off, and outputs will be running.

### Power Connections

Pin Number			Description
VDD	VDDIO	GND	
5		8	Input receiver analog
12		9	Digital Power
20,31,38	13,21,31,39,47	22,29,40	DIF outputs
30		29	PLL Analog

Note: epad on this device is not electrically connected to the die. It should be connected to ground for best thermal performance.

### PLL Operating Mode

HiBW_BypM LoBW#	MODE	Byte1 [7:6] Readback	Byte1 [4:3] Control
0	PLL Lo BW	00	00
M	Bypass	01	01
1	PLL Hi BW	11	11

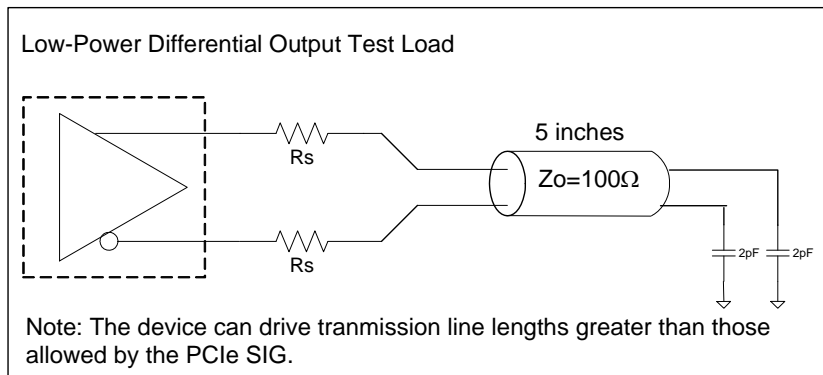
## Pin Descriptions

PIN #	PIN NAME	TYPE	DESCRIPTION
1	vSADR_tri	LATCHED IN	Tri-level latch to select SMBus Address. See SMBus Address Selection Table.
2	^vHIBW_BYPM_LOBW#	LATCHED IN	Trilevel input to select High BW, Bypass or Low BW mode. See PLL Operating Mode Table for Details.
3	FB_DNC	DNC	True clock of differential feedback. The feedback output and feedback input are connected internally on this pin. Do not connect anything to this pin.
4	FB_DNC#	DNC	Complement clock of differential feedback. The feedback output and feedback input are connected internally on this pin. Do not connect anything to this pin.
5	VDDR1.5	PWR	1.5V power for differential input clock (receiver). This VDD should be treated as an Analog power rail and filtered appropriately.
6	CLK_IN	IN	True Input for differential reference clock.
7	CLK_IN#	IN	Complementary Input for differential reference clock.
8	GNDR	GND	Analog Ground pin for the differential input (receiver)
9	GNDDIG	GND	Ground pin for digital circuitry
10	SCLK_3.3	IN	Clock pin of SMBus circuitry, 3.3V tolerant.
11	SDATA_3.3	I/O	Data pin for SMBus circuitry, 3.3V tolerant.
12	VDDDIG1.5	PWR	1.5V digital power (dirty power)
13	VDDIO	PWR	Power supply for differential outputs
14	vOE0#	IN	Active low input for enabling DIF pair 0. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
15	DIF0	OUT	Differential true clock output
16	DIF0#	OUT	Differential Complementary clock output
17	vOE1#	IN	Active low input for enabling DIF pair 1. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
18	DIF1	OUT	Differential true clock output
19	DIF1#	OUT	Differential Complementary clock output
20	VDD1.5	PWR	Power supply, nominally 1.5V
21	VDDIO	PWR	Power supply for differential outputs
22	GND	GND	Ground pin.
23	DIF2	OUT	Differential true clock output
24	DIF2#	OUT	Differential Complementary clock output
25	vOE2#	IN	Active low input for enabling DIF pair 2. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
26	DIF3	OUT	Differential true clock output
27	DIF3#	OUT	Differential Complementary clock output
28	vOE3#	IN	Active low input for enabling DIF pair 3. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
29	GNDA	GND	Ground pin for the PLL core.
30	VDDA1.5	PWR	1.5V power for the PLL core.
31	VDDIO	PWR	Power supply for differential outputs
32	DIF4	OUT	Differential true clock output
33	DIF4#	OUT	Differential Complementary clock output
34	vOE4#	IN	Active low input for enabling DIF pair 4. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
35	DIF5	OUT	Differential true clock output
36	DIF5#	OUT	Differential Complementary clock output
37	vOE5#	IN	Active low input for enabling DIF pair 5. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
38	VDD1.5	PWR	Power supply, nominally 1.5V
39	VDDIO	PWR	Power supply for differential outputs
40	GND	GND	Ground pin.

## Pin Descriptions (cont.)

PIN #	PIN NAME	TYPE	DESCRIPTION
41	DIF6	OUT	Differential true clock output
42	DIF6#	OUT	Differential Complementary clock output
43	vOE6#	IN	Active low input for enabling DIF pair 6. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
44	DIF7	OUT	Differential true clock output
45	DIF7#	OUT	Differential Complementary clock output
46	vOE7#	IN	Active low input for enabling DIF pair 7. This pin has an internal pull-down. 1 =disable outputs, 0 = enable outputs
47	VDDIO	PWR	Power supply for differential outputs
48	^CKPWRGD_PD#	IN	Input notifies device to sample latched inputs and start up on first high assertion. Low enters Power Down Mode, subsequent high assertions exit Power Down Mode. This pin has internal pull-up resistor.
49	EPAD	GND	Connect ePAD to ground.

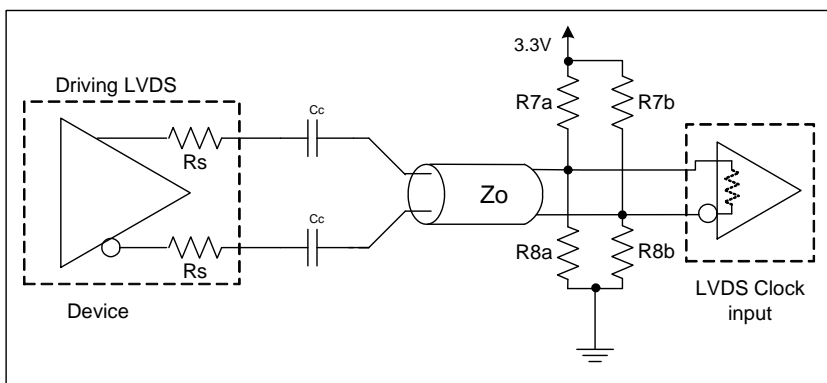
## Test Loads



### Alternate Differential Output Terminations

Rs	Zo	Units
33	100	Ohms
27	85	

## Driving LVDS



### Driving LVDS inputs

Component	Value		Note
	Receiver has termination	Receiver does not have termination	
R7a, R7b	10K ohm	140 ohm	
R8a, R8b	5.6K ohm	75 ohm	
Cc	0.1 uF	0.1 uF	
Vcm	1.2 volts	1.2 volts	

## Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 9DBU0831. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Supply Voltage	VDDx		-0.5		2	V	1,2
Input Voltage	V <sub>IN</sub>		-0.5		V <sub>DD</sub> +0.5	V	1,3
Input High Voltage, SMBus	V <sub>IHSMB</sub>	SMBus clock and data pins			3.3	V	1
Storage Temperature	T <sub>s</sub>		-65		150	°C	1
Junction Temperature	T <sub>j</sub>				125	°C	1
Input ESD protection	ESD prot	Human Body Model	2000			V	1

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup>Operation under these conditions is neither implied nor guaranteed.

<sup>3</sup>Not to exceed 2.0V.

## Electrical Characteristics–Clock Input Parameters

TA = T<sub>AMB</sub>, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input Common Mode Voltage - DIF_IN	V <sub>COM</sub>	Common Mode Input Voltage	200		725	mV	1
Input Swing - DIF_IN	V <sub>SWING</sub>	Differential value	300		1450	mV	1
Input Slew Rate - DIF_IN	dv/dt	Measured differentially	0.4		8	V/ns	1,2
Input Leakage Current	I <sub>IN</sub>	V <sub>IN</sub> = V <sub>DD</sub> , V <sub>IN</sub> = GND	-5		5	uA	
Input Duty Cycle	d <sub>tin</sub>	Measurement from differential waveform	45	50	55	%	1
Input Jitter - Cycle to Cycle	J <sub>DIFIN</sub>	Differential Measurement	0		150	ps	1

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup>Slew rate measured through +/-75mV window centered around differential zero

## Electrical Characteristics–Input/Supply/Common Parameters–Normal Operating Conditions

TA = T<sub>AMB</sub>, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Supply Voltage	VDDx	Supply voltage for core and analog	1.425	1.5	1.575	V	
Output Supply Voltage	VDDIO	Supply voltage for Low Power HCSL Outputs	0.95	1.05	1.575	V	
Ambient Operating Temperature	T <sub>AMB</sub>	Commercial range	0	25	70	°C	1
		Industrial range	-40	25	85	°C	1
Input High Voltage	V <sub>IH</sub>	Single-ended inputs, except SMBus	0.75 V <sub>DD</sub>		V <sub>DD</sub> + 0.3	V	
Input Mid Voltage	V <sub>IM</sub>	Single-ended tri-level inputs ('_tri' suffix)	0.4 V <sub>DD</sub>		0.6 V <sub>DD</sub>	V	
Input Low Voltage	V <sub>IL</sub>	Single-ended inputs, except SMBus	-0.3		0.25 V <sub>DD</sub>	V	
Input Current	I <sub>IN</sub>	Single-ended inputs, V <sub>IN</sub> = GND, V <sub>IN</sub> = VDD	-5		5	uA	
	I <sub>INP</sub>	Single-ended inputs V <sub>IN</sub> = 0 V; Inputs with internal pull-up resistors V <sub>IN</sub> = VDD; Inputs with internal pull-down resistors	-200		200	uA	
Input Frequency	F <sub>ibyp</sub>	Bypass mode	1		167	MHz	2
	F <sub>ipll</sub>	100MHz PLL mode	60	100.00	110	MHz	2
Pin Inductance	L <sub>pin</sub>				7	nH	1
Capacitance	C <sub>IN</sub>	Logic Inputs, except DIF_IN	1.5		5	pF	1
	C <sub>INDIF_IN</sub>	DIF_IN differential clock inputs	1.5		2.7	pF	1,5
	C <sub>OUT</sub>	Output pin capacitance			6	pF	1
Clk Stabilization	T <sub>STAB</sub>	From V <sub>DD</sub> Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock			1	ms	1,2
Input SS Modulation Frequency PCIe	f <sub>MODINPCIe</sub>	Allowable Frequency for PCIe Applications (Triangular Modulation)	30		33	kHz	
Input SS Modulation Frequency non-PCIe	f <sub>MODIN</sub>	Allowable Frequency for non-PCIe Applications (Triangular Modulation)	0		66	kHz	
OE# Latency	t <sub>LATOE#</sub>	DIF start after OE# assertion DIF stop after OE# deassertion	1		3	clocks	1,3
Tdrive_PD#	t <sub>DRVPD</sub>	DIF output enable after PD# de-assertion			300	us	1,3
Tfall	t <sub>F</sub>	Fall time of single-ended control inputs			5	ns	2
Trise	t <sub>R</sub>	Rise time of single-ended control inputs			5	ns	2
SMBus Input Low Voltage	V <sub>ILSMB</sub>				0.6	V	
SMBus Input High Voltage	V <sub>IHSMB</sub>	V <sub>DD</sub> SMB = 3.3V, see note 4 for V <sub>DD</sub> SMB < 3.3V	2.1		3.3	V	4
SMBus Output Low Voltage	V <sub>OLSMB</sub>	@ I <sub>PULLUP</sub>			0.4	V	
SMBus Sink Current	I <sub>PULLUP</sub>	@ V <sub>OL</sub>	4			mA	
Nominal Bus Voltage	V <sub>DD</sub> SMB	Bus Voltage	1.425		3.3	V	
SCLK/SDATA Rise Time	t <sub>RSMB</sub>	(Max VIL - 0.15) to (Min VIH + 0.15)			1000	ns	1
SCLK/SDATA Fall Time	t <sub>FSMB</sub>	(Min VIH + 0.15) to (Max VIL - 0.15)			300	ns	1
SMBus Operating Frequency	f <sub>MAXSMB</sub>	Maximum SMBus operating frequency			400	kHz	7

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup>Control input must be monotonic from 20% to 80% of input swing.

<sup>3</sup>Time from deassertion until outputs are >200 mV

<sup>4</sup> For V<sub>DD</sub>SMB < 3.3V, V<sub>IHSMB</sub> >= 0.8xV<sub>DD</sub>SMB

<sup>5</sup>DIF\_IN input

<sup>6</sup>The differential input clock must be running for the SMBus to be active

## Electrical Characteristics–DIF Low-Power HCSL Outputs

TA = T<sub>AMB</sub>, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Slew rate	dV/dt	Scope averaging on, fast setting	1.4	2.2	3.5	V/ns	1,2,3
	dV/dt	Scope averaging on, slow setting	0.9	1.7	2.5	V/ns	1,2,3
Slew rate matching	ΔV/dt	Slew rate matching, Scope averaging on		2.7	20	%	1,2,4
Voltage High	V <sub>HIGH</sub>	Statistical measurement on single-ended signal using oscilloscope math function. (Scope averaging on)	630	735	850	mV	7
Voltage Low	V <sub>LOW</sub>		-150	-16	150		7
Max Voltage	V <sub>max</sub>	Measurement on single ended signal using absolute value. (Scope averaging off)		779	1150	mV	7
Min Voltage	V <sub>min</sub>		-300	-45			7
Vswing	Vswing	Scope averaging off	300	1503		mV	1,2
Crossing Voltage (abs)	V <sub>cross_abs</sub>	Scope averaging off	250	405	550	mV	1,5
Crossing Voltage (var)	Δ-V <sub>cross</sub>	Scope averaging off		12	140	mV	1,6

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup> Measured from differential waveform

<sup>3</sup> Slew rate is measured through the Vswing voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

<sup>4</sup> Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

<sup>5</sup> V<sub>cross</sub> is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

<sup>6</sup> The total variation of all V<sub>cross</sub> measurements in any particular system. Note that this is a subset of V<sub>cross\_min/max</sub> (V<sub>cross</sub> absolute) allowed. The intent is to limit V<sub>cross</sub> induced modulation by setting Δ-V<sub>cross</sub> to be smaller than V<sub>cross</sub> absolute.

<sup>7</sup> At default SMBus settings.

## Electrical Characteristics–Current Consumption

TA = T<sub>AMB</sub>, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Operating Supply Current	I <sub>DDA</sub>	VDDA+VDDR, PLL Mode, @100MHz		11	15	mA	
	I <sub>DD</sub>	VDD, All outputs active @100MHz		6	9	mA	
	I <sub>DDIO</sub>	VDDIO, All outputs active @100MHz		28	35	mA	
Powerdown Current	I <sub>DDAPD</sub>	VDDA+VDDR, CKPWRGD_PD#=0		0.5	1	mA	2
	I <sub>DDPD</sub>	VDDx, CKPWRGD_PD#=0		0.6	1	mA	2
	I <sub>DDIOPD</sub>	VDDIO, CKPWRGD_PD#=0		0.003	0.01	mA	2

<sup>1</sup> Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup> Input clock stopped.

## Electrical Characteristics–Output Duty Cycle, Jitter, Skew and PLL Characteristics

TA = T<sub>AMB</sub>, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
PLL Bandwidth	BW	-3dB point in High BW Mode (100MHz)	2.3	3.6	4.7	MHz	1,5
		-3dB point in Low BW Mode (100MHz)	1	1.6	2.5	MHz	1,5
PLL Jitter Peaking	t <sub>JPEAK</sub>	Peak Pass band Gain (100MHz)		1.3	2.5	dB	1
Duty Cycle	t <sub>DC</sub>	Measured differentially, PLL Mode	45	50	55	%	1
Duty Cycle Distortion	t <sub>DCD</sub>	Measured differentially, Bypass Mode	-1	-0.6	0	%	1,3
Skew, Input to Output	t <sub>pdBYP</sub>	Bypass Mode, V <sub>T</sub> = 50%	3400	4301	5200	ps	1
	t <sub>pdPLL</sub>	PLL Mode V <sub>T</sub> = 50%	0	50	150	ps	1,4
Skew, Output to Output	t <sub>sk3</sub>	V <sub>T</sub> = 50%		37	75	ps	1,4
		PLL mode		24	50	ps	1,2
Jitter, Cycle to cycle	t <sub>jcy-cyc</sub>	Additive Jitter in Bypass Mode		0.1	10	ps	1,2

<sup>1</sup> Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup> Measured from differential waveform

<sup>3</sup> Duty cycle distortion is the difference in duty cycle between the output and the input clock when the device is operated in bypass mode.

<sup>4</sup> All outputs at default slew rate

<sup>5</sup> The MIN/TYP/MAX values of each BW setting track each other, i.e., Low BW MAX will never occur with Hi BW MIN.

## Electrical Characteristics–Phase Jitter Parameters

TA = T<sub>AMB</sub>, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	INDUSTRY LIMIT	UNITS	Notes
Phase Jitter, PLL Mode	t <sub>jphPCIEG1</sub>	PCIe Gen 1		30	58	86	ps (p-p)	1,2,3,5
	t <sub>jphPCIEG2</sub>	PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz		0.9	1.4	3	ps (rms)	1,2,3,5
		PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		2.1	2.6	3.1	ps (rms)	1,2,3,5
	t <sub>jphPCIEG3</sub>	PCIe Gen 3 Common Clock Architecture (PLL BW of 2-4 or 2-5MHz, CDR = 10MHz)		0.5	0.6	1	ps (rms)	1,2,3,5
t <sub>jphPCIEG3SRns</sub>	PCIe Gen 3 Separate Reference No Spread (SRnS) (PLL BW of 2-4 or 2-5MHz, CDR = 10MHz)		0.5	0.6	0.7	ps (rms)	1,2,3,5	
Additive Phase Jitter, Bypass Mode	t <sub>jphPCIEG1</sub>	PCIe Gen 1		0.1	5	N/A	ps (p-p)	1,2,3,5
	t <sub>jphPCIEG2</sub>	PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz		0.1	0.5	N/A	ps (rms)	1,2,3,4,5
		PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		0.1	0.7	N/A	ps (rms)	1,2,3,4
	t <sub>jphPCIEG3</sub>	PCIe Gen 3 (PLL BW of 2-4 or 2-5MHz, CDR = 10MHz)		0.2	0.3	N/A	ps (rms)	1,2,3,4
	t <sub>jph125M0</sub>	125MHz, 1.5MHz to 10MHz, -20dB/decade rollover < 1.5MHz, -40db/decade rolloff > 10MHz		200	250	N/A	fs (rms)	1,6
t <sub>jph125M1</sub>	125MHz, 12KHz to 20MHz, -20dB/decade rollover < 1.5MHz, -40db/decade rolloff > 10MHz		313	350	N/A	fs (rms)	1,6	

<sup>1</sup> Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup> See <http://www.pcisig.com> for complete specs

<sup>3</sup> Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

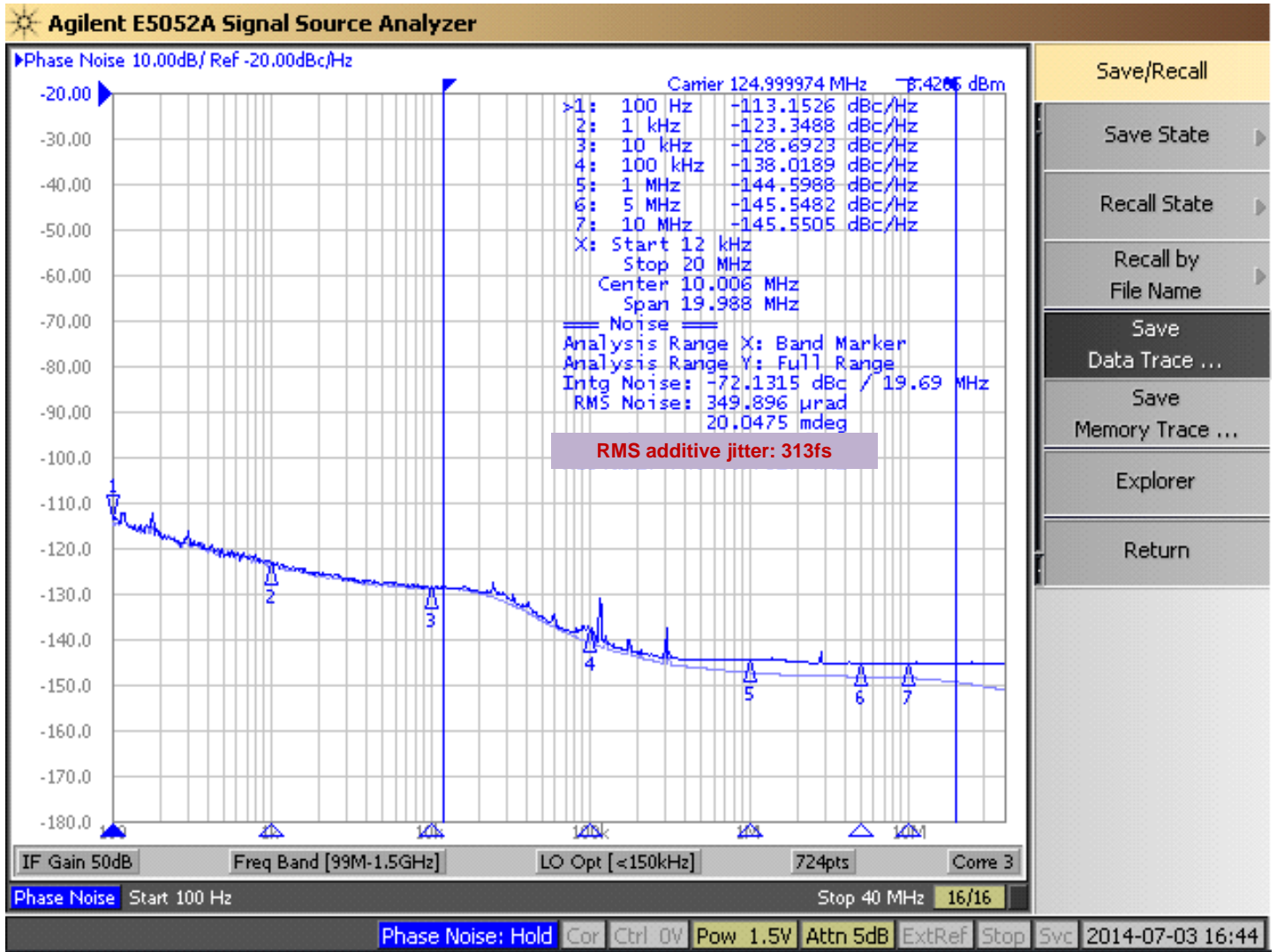
<sup>4</sup> For RMS figures, additive jitter is calculated by solving the following equation: Additive jitter = SQRT[(total jitter)<sup>2</sup> - (input jitter)<sup>2</sup>]

<sup>5</sup> Driven by 9FGU0831 or equivalent

<sup>6</sup> Rohde&Schartz SMA100



### Additive Phase Jitter Plot: 125M (12kHz to 20MHz)



## General SMBus Serial Interface Information

### How to Write

- Controller (host) sends a start bit
- Controller (host) sends the write address
- IDT clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- IDT clock will **acknowledge**
- Controller (host) sends the byte count = X
- IDT clock will **acknowledge**
- Controller (host) starts sending Byte N through Byte N+X-1
- IDT clock will **acknowledge** each byte **one at a time**
- Controller (host) sends a Stop bit

Index Block Write Operation			
Controller (Host)			IDT (Slave/Receiver)
T	starT bit		
Slave Address			
WR	WRite		
			ACK
Beginning Byte = N			
			ACK
Data Byte Count = X			
			ACK
Beginning Byte N		X Byte	
O			ACK
O			O
O			O
O			O
Byte N + X - 1			
			ACK
P	stoP bit		

**Note: SMBus Address is Latched on SADR pin.**

### How to Read

- Controller (host) will send a start bit
- Controller (host) sends the write address
- IDT clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- IDT clock will **acknowledge**
- Controller (host) will send a separate start bit
- Controller (host) sends the read address
- IDT clock will **acknowledge**
- IDT clock will send the data byte count = X
- IDT clock sends Byte N+X-1
- IDT clock sends **Byte 0 through Byte X (if X<sub>(H)</sub> was written to Byte 8)**
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

Index Block Read Operation			
Controller (Host)			IDT (Slave/Receiver)
T	starT bit		
Slave Address			
WR	WRite		
			ACK
Beginning Byte = N			
			ACK
RT	Repeat starT		
Slave Address			
RD	ReaD		
			ACK
			Data Byte Count=X
ACK		X Byte	
ACK			Beginning Byte N
			O
			O
			O
			Byte N + X - 1
N	Not acknowledge		
P	stoP bit		

**SMBus Table: Output Enable Register <sup>1</sup>**

Byte 0	Name	Control Function	Type	0	1	Default
Bit 7	DIF OE7	Output Enable	RW	Low/Low	Enabled	1
Bit 6	DIF OE6	Output Enable	RW	Low/Low	Enabled	1
Bit 5	DIF OE5	Output Enable	RW	Low/Low	Enabled	1
Bit 4	DIF OE4	Output Enable	RW	Low/Low	Enabled	1
Bit 3	DIF OE3	Output Enable	RW	Low/Low	Enabled	1
Bit 2	DIF OE2	Output Enable	RW	Low/Low	Enabled	1
Bit 1	DIF OE1	Output Enable	RW	Low/Low	Enabled	1
Bit 0	DIF OE0	Output Enable	RW	Low/Low	Enabled	1

1. A low on these bits will override the OE# pin and force the differential output Low/Low

**SMBus Table: PLL Operating Mode and Output Amplitude Control Register**

Byte 1	Name	Control Function	Type	0	1	Default
Bit 7	PLLMODERB1	PLL Mode Readback Bit 1	R	See PLL Operating Mode Table		Latch
Bit 6	PLLMODERB0	PLL Mode Readback Bit 0	R			Latch
Bit 5	PLLMODE_SWCNTRL	Enable SW control of PLL Mode	RW	Values in B1[7:6] set PLL Mode	Values in B1[4:3] set PLL Mode	0
Bit 4	PLLMODE1	PLL Mode Control Bit 1	RW <sup>1</sup>	See PLL Operating Mode Table		0
Bit 3	PLLMODE0	PLL Mode Control Bit 0	RW <sup>1</sup>			0
Bit 2	Reserved					1
Bit 1	AMPLITUDE 1	Controls Output Amplitude	RW	00 = 0.55V	01 = 0.65V	1
Bit 0	AMPLITUDE 0		RW	10 = 0.7V	11 = 0.8V	0

1. B1[5] must be set to a 1 for these bits to have any effect on the part.

**SMBus Table: DIF Slew Rate Control Register**

Byte 2	Name	Control Function	Type	0	1	Default
Bit 7	SLEWRATESEL DIF7	Adjust Slew Rate of DIF7	RW	Slow Setting	Fast Setting	1
Bit 6	SLEWRATESEL DIF6	Adjust Slew Rate of DIF6	RW	Slow Setting	Fast Setting	1
Bit 5	SLEWRATESEL DIF5	Adjust Slew Rate of DIF5	RW	Slow Setting	Fast Setting	1
Bit 4	SLEWRATESEL DIF4	Adjust Slew Rate of DIF4	RW	Slow Setting	Fast Setting	1
Bit 3	SLEWRATESEL DIF3	Adjust Slew Rate of DIF3	RW	Slow Setting	Fast Setting	1
Bit 2	SLEWRATESEL DIF2	Adjust Slew Rate of DIF2	RW	Slow Setting	Fast Setting	1
Bit 1	SLEWRATESEL DIF1	Adjust Slew Rate of DIF1	RW	Slow Setting	Fast Setting	1
Bit 0	SLEWRATESEL DIF0	Adjust Slew Rate of DIF0	RW	Slow Setting	Fast Setting	1

Note: See "Low-Power HCSL Outputs" table for slew rates.

**SMBus Table: Frequency Select Control Register**

Byte 3	Name	Control Function	Type	0	1	Default
Bit 7		Reserved				1
Bit 6		Reserved				1
Bit 5		Reserved				0
Bit 4		Reserved				0
Bit 3		Reserved				0
Bit 2		Reserved				1
Bit 1		Reserved				1
Bit 0	SLEWRATESEL FB	Adjust Slew Rate of FB	RW	Slow Setting	Fast Setting	1

Byte 4 is Reserved and reads back 'hFF'

**SMBus Table: Revision and Vendor ID Register**

Byte 5	Name	Control Function	Type	0	1	Default
Bit 7	RID3	Revision ID	R	A rev		0
Bit 6	RID2		R			0
Bit 5	RID1		R			0
Bit 4	RID0		R			1
Bit 3	VID3	VENDOR ID	R	0001 = IDT		0
Bit 2	VID2		R			0
Bit 1	VID1		R			0
Bit 0	VID0		R			1

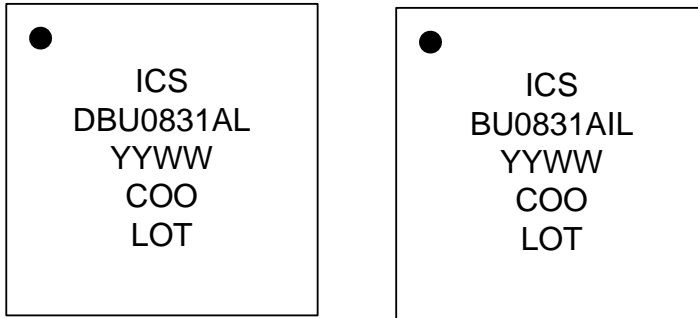
**SMBus Table: Device Type/Device ID**

Byte 6	Name	Control Function	Type	0	1	Default
Bit 7	Device Type1	Device Type	R	00 = FGx, 01 = DBx ZDB/FOB, 10 = DMx, 11= DBx FOB		0
Bit 6	Device Type0		R			1
Bit 5	Device ID5	Device ID	R	001000 binary or 08 hex		0
Bit 4	Device ID4		R			0
Bit 3	Device ID3		R			1
Bit 2	Device ID2		R			0
Bit 1	Device ID1		R			0
Bit 0	Device ID0		R			0

**SMBus Table: Byte Count Register**

Byte 7	Name	Control Function	Type	0	1	Default
Bit 7	Reserved					0
Bit 6	Reserved					0
Bit 5	Reserved					0
Bit 4	BC4	Byte Count Programming	RW	Writing to this register will configure how many bytes will be read back, default is = 8 bytes.		0
Bit 3	BC3		RW			1
Bit 2	BC2		RW			0
Bit 1	BC1		RW			0
Bit 0	BC0		RW			0

## Marking Diagrams



### Notes:

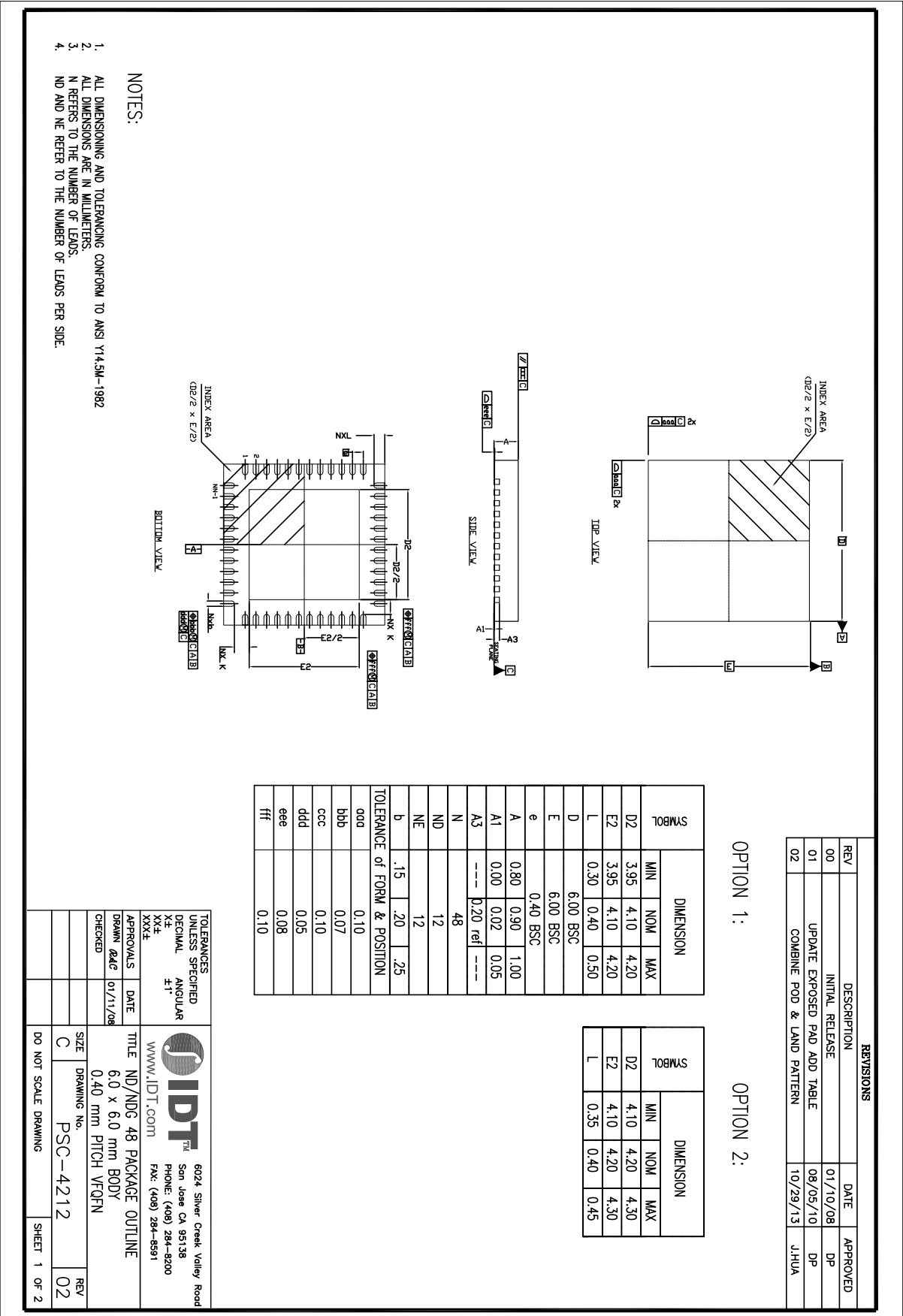
1. "LOT" is the lot sequence number.
2. "COO" denotes country of origin.
3. YYWW is the last two digits of the year and week that the part was assembled.
4. Line 2: truncated part number
5. "L" denotes RoHS compliant package.
6. "I" denotes industrial temperature range device.

## Thermal Characteristics

PARAMETER	SYMBOL	CONDITIONS	PKG	TYP VALUE	UNITS	NOTES
Thermal Resistance	$\theta_{JC}$	Junction to Case	NDG48	33	°C/W	1
	$\theta_{Jb}$	Junction to Base		2.1	°C/W	1
	$\theta_{JA00}$	Junction to Air, still air		37	°C/W	1
	$\theta_{JA1}$	Junction to Air, 1 m/s air flow		30	°C/W	1
	$\theta_{JA3}$	Junction to Air, 3 m/s air flow		27	°C/W	1
	$\theta_{JA5}$	Junction to Air, 5 m/s air flow		26	°C/W	1

<sup>1</sup>ePad soldered to board

# Package Outline and Package Dimensions (NDG48) – use EPAD Option P1



1. ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. N REFERS TO THE NUMBER OF LEADS.
4. ND AND NE REFER TO THE NUMBER OF LEADS PER SIDE.

**NOTES:**

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	01/10/08	DP
01	UPDATE EXPOSED PAD ADD TABLE	08/05/10	DP
02	COMBINE POD & LAND PATTERN	10/29/13	J.HUA

OPTION 1:

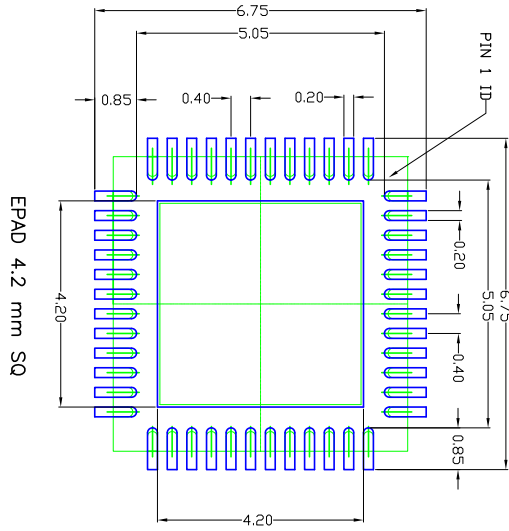
OPTION 2:

SYMBOL	DIMENSION		
	MIN	NOM	MAX
D2	3.95	4.10	4.20
E2	3.95	4.10	4.20
L	0.30	0.40	0.50
D	6.00 BSC		
E	6.00 BSC		
e	0.40 BSC		
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3	0.20 ref ---		
N	48		
ND	12		
NE	12		
b	.15	.20	.25
TOLERANCE of FORM & POSITION			
ddd	0.10		
bbb	0.07		
ccc	0.10		
ddd	0.05		
eee	0.08		
fff	0.10		

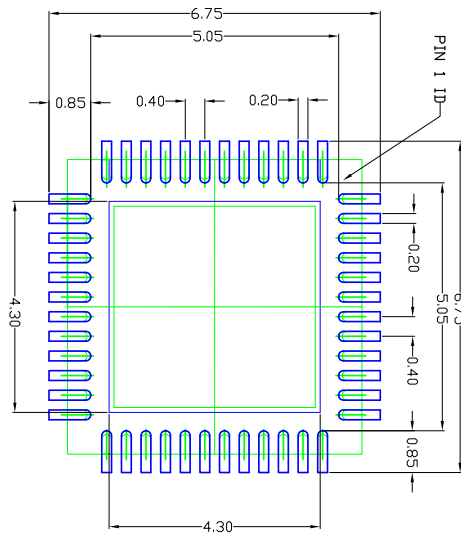
SYMBOL	DIMENSION		
	MIN	NOM	MAX
D2	4.10	4.20	4.30
E2	4.10	4.20	4.30
L	0.35	0.40	0.45

<b>TOLERANCES</b> UNLESS SPECIFIED DECIMAL     ANGULAR XXX+        ±1 XXXF APPROVALS     DATE DRAWN <i>dadg</i> 01/11/08 CHECKED _____		6024 Silver Creek Valley Road San Jose CA 95138 PHONE: (408) 294-8200 FAX: (408) 294-6591 www.IDT.com	
TITLE ND/NDG 48 PACKAGE OUTLINE DRAWN <i>dadg</i> CHECKED _____		BODY 6.0 x 6.0 mm 0.40 mm PITCH VFOFN DRAWING No. PSC-4212 SIZE C DO NOT SCALE DRAWING	
REV 02		SHEET 1 OF 2	

Package Outline and Package Dimensions (NDG48) – use EPAD 4.2 mm SQ




EPAD 4.2 mm SQ



EPAD 4.3 mm SQ

- NOTES:
1. ALL DIMENSION ARE IN MM. ANGLES IN DEGREES.
  2. TOP DOWN VIEW, AS VIEWED ON POB.
  3. COMPONENT OUTLINE SHOW FOR REFERENCE IN GREEN.
  4. LAND PATTERN IN BLUE, NSMD PATTERN ASSUMED.
  5. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	01/10/08	DP
01	UPDATE EXPOSED PAD ADD TABLE	08/05/10	DP
02	COMBINE PAD & LAND PATTERN	10/29/13	JHUA

TOLERANCES UNLESS SPECIFIED	DECIMAL	ANGULAR	±1°
XXX	XXX	XXX	XXX
APPROVALS	DATE	 6024 Silver Creek Valley Road San Jose CA 95138 PHONE: (408) 294-8200 FAX: (408) 294-8591 WWW.IDT.COM	
DRAWN /RAG	01/11/08	TITLE ND/NDG_48 PACKAGE OUTLINE 6.0 x 6.0 mm BODY 0.40 mm PITCH VFOFN	
CHECKED		SIZE	DRAWING No.
		C	PSC-4212
		DO NOT SCALE DRAWING	REV 02
			SHEET 2 OF 2

## Ordering Information

Part / Order Number	Shipping Packaging	Package	Temperature
9DBU0831AKLF	Trays	48-pin VFQFPN	0 to +70° C
9DBU0831AKLFT	Tape and Reel	48-pin VFQFPN	0 to +70° C
9DBU0831AKILF	Trays	48-pin VFQFPN	-40 to +85° C
9DBU0831AKILFT	Tape and Reel	48-pin VFQFPN	-40 to +85° C

"LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

"A" is the device revision designator (will not correlate with the datasheet revision).

## Revision History

Rev.	Issue Date	Initiator	Description	Page #
A	RDW	7/14/2014	<ol style="list-style-type: none"> <li>Updated electrical tables with char data.</li> <li>Added an additive phase jitter plot.</li> <li>Added 12kHz to 20MHz <i>additive</i> phase jitter spec.</li> <li>Updated Amplitude control bit <i>descriptions</i> in Byte 1.</li> </ol>	Various
B	RDW	9/19/2014	Updated SMBus Input High/Low parameters conditions, MAX values, and footnotes.	6
C	RDW	4/17/2015	<ol style="list-style-type: none"> <li>Updated Key Specifications to be consistent acrosss the family.</li> <li>Updated pin out and pin descriptions to show ePad on package connected to ground.</li> <li>Updated Clock Input Parameters table to be consistent with PCIe Vswing parameter.</li> </ol>	1-6





**Corporate Headquarters**  
6024 Silver Creek Valley Road  
San Jose, CA 95138 USA

**Sales**  
1-800-345-7015 or 408-284-8200  
Fax: 408-284-2775  
www.IDT.com

**Tech Support**  
email: [clocks@idt.com](mailto:clocks@idt.com)

DISCLAIMER Integrated Device Technology, Inc. (IDT) and its subsidiaries reserve the right to modify the products and/or specifications described herein at any time and at IDT's sole discretion. All information in this document, including descriptions of product features and performance, is subject to change without notice. Performance specifications and the operating parameters of the described products are determined in the independent state and are not guaranteed to perform the same way when installed in customer products. The information contained herein is provided without representation or warranty of any kind, whether express or implied, including, but not limited to, the suitability of IDT's products for any particular purpose, an implied warranty of merchantability, or non-infringement of the intellectual property rights of others. This document is presented only as a guide and does not convey any license under intellectual property rights of IDT or any third parties.

IDT's products are not intended for use in applications involving extreme environmental conditions or in life support systems or similar devices where the failure or malfunction of an IDT product can be reasonably expected to significantly affect the health or safety of users. Anyone using an IDT product in such a manner does so at their own risk, absent an express, written agreement by IDT.

Integrated Device Technology, IDT and the IDT logo are registered trademarks of IDT. Product specification subject to change without notice. Other trademarks and service marks used herein, including protected names, logos and designs, are the property of IDT or their respective third party owners.

Copyright ©2015 Integrated Device Technology, Inc.. All rights reserved.